

In situ low-angle x-ray scattering study of phase separation at initially mixed HfO_2 - SiO_2 thin film interfaces

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Motivation



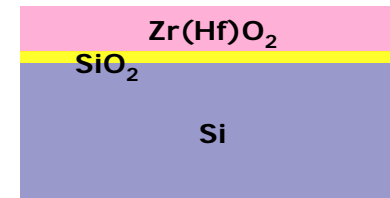
Subsequent high temperature thermal processing causes **phase separation**
G.Lucovsky et al, Appl.Phys.Lett. 77, 2912 (2000)



Loss of desired dielectric and electrical properties



Need to investigate **effects of phase separation** upon thermal process



Metal oxide/SiO₂ interface structure uncertain due to deposition-induced mixing and thermal instability



Loss of desired dielectric and electrical properties



Need to understand **abruptness and stability** of metal oxide/SiO₂ interfaces



Phase separation of Hf-silicate films forms $\text{HfO}_2/\text{SiO}_2$ interfaces

- Initially intermixed $\text{HfO}_2\text{-SiO}_2$ alloy experiences a driving force for phase separation upon annealing



- Form regions of crystalline HfO_2 and amorphous SiO_2

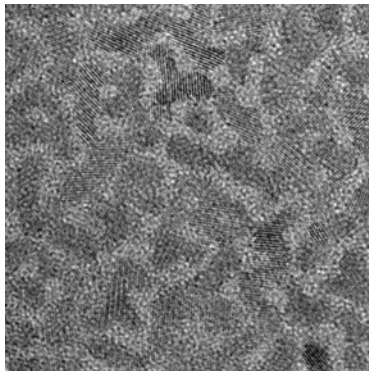
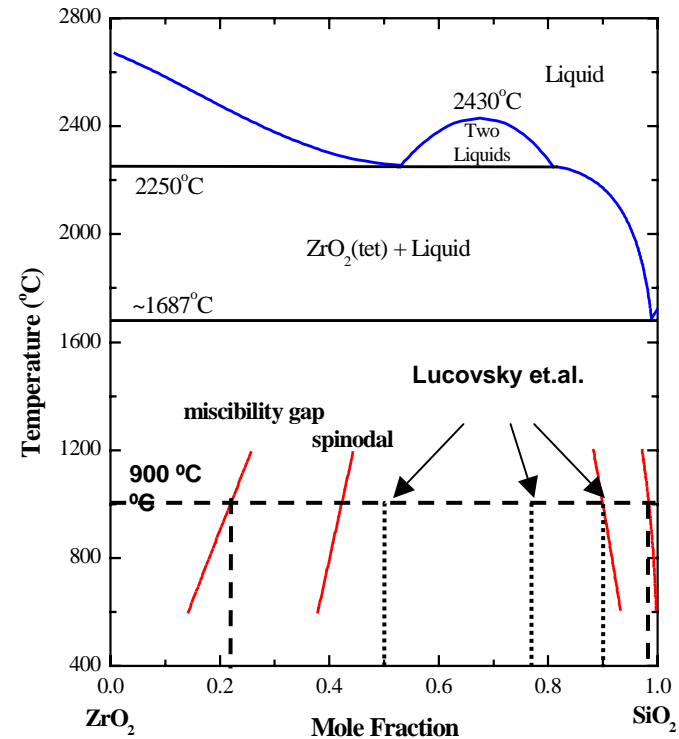


Image courtesy of S. Stemmer



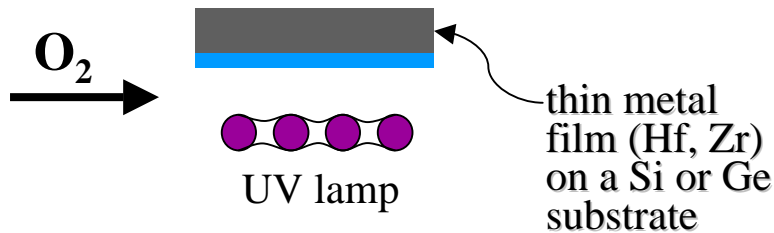
H. Kim et al., *J. Appl. Phys.* (2002).

S. Stemmer et al., *Jpn. J. Appl. Phys.* (2003).

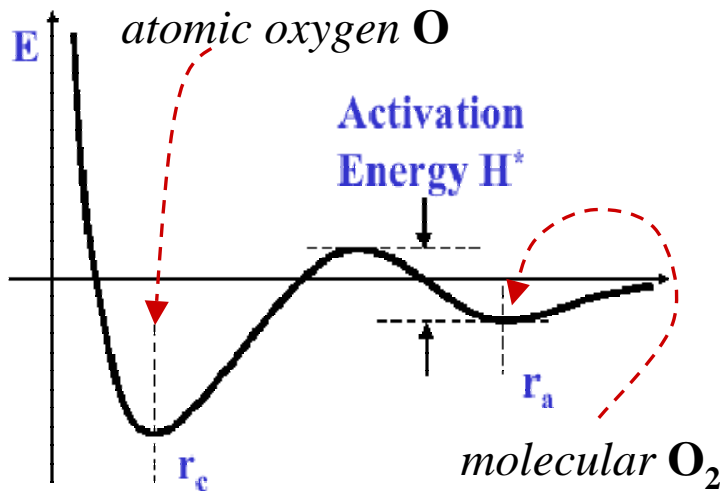
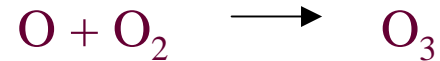
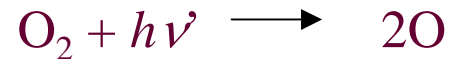
Lucovsky et al., *Appl. Phys. Lett.* (2000).



Growth of Metal Oxide Dielectrics : UV-Ozone Oxidation



- UV light supplies atomic oxygen and ozone to surface through the following reactions:

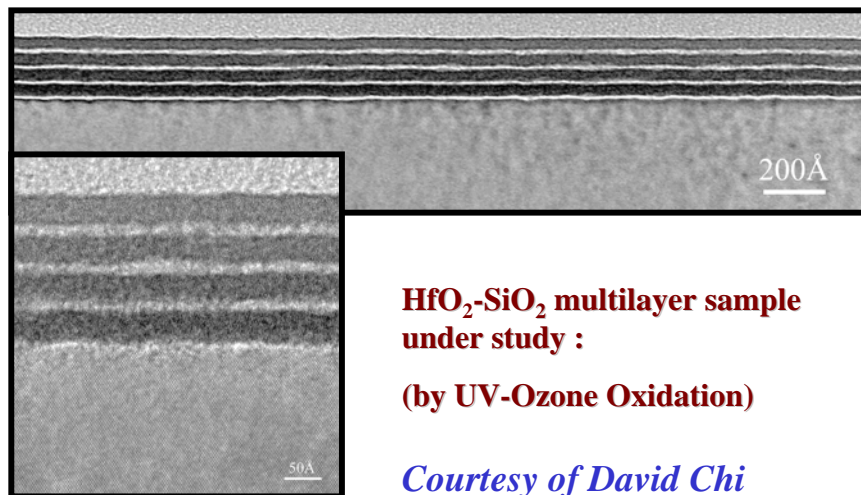


- Benefits
 - Low temperature
 - Low contamination
 - Simplicity
 - Can modify substrate surface passivation

S. Ramanathan et al., Appl. Phys. Lett. (2001)



Multilayer test structure for HfO₂/SiO₂ interfaces



- (1.4nm SiO₂ / 4nm HfO₂)₄ structure on top of Si (100) substrate
- Grown by UVO oxidation
- Growth conditions
 - Hf, Si sputtered in 2 mTorr Ar pressure (~0.2 Å/sec) with base pressure 5E-9 Torr
 - Oxidized for 1 hr at 600 Torr O₂ pressure in UV light

* Advantage of using multilayers :

- Deliberate exaggeration of particular interface effects
- Separation of interface effects on electrical properties by comparing multi- and single layers



X-ray diffraction: probe of local electron density

The scattered amplitude of the x-ray diffraction from the given system is just proportional to the Fourier transform of the local electron density :

$$\varepsilon_c = \frac{E_0 r_e}{R} \exp[i(\omega t - kR)] \int e^{iq \cdot r} \rho_c(r) dV$$

so that $I \propto \left(\int e^{iq \cdot r} \rho_c(r) dV \right)^2$

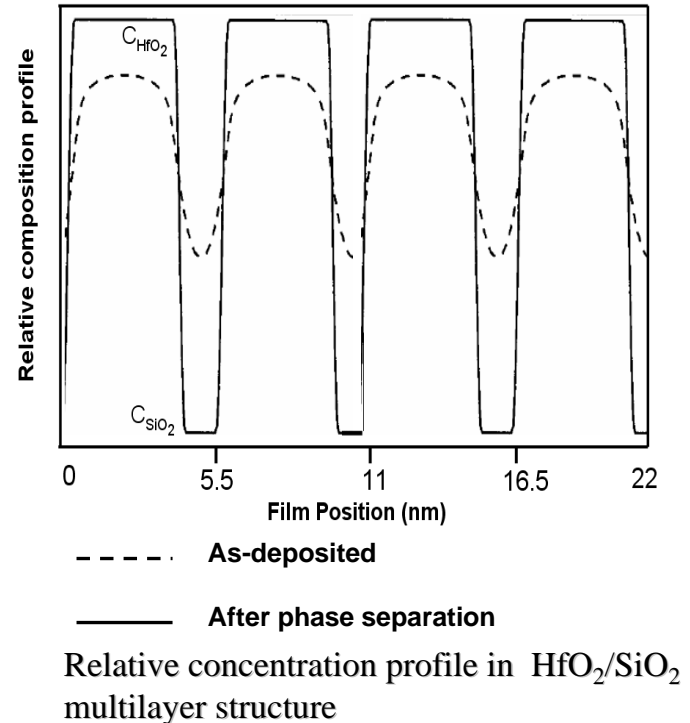
E_0 : electric field magnitude
 r_e : electron radius
 R : distance from the sample to the detector
 q : scattering vector
 $\rho_c(r)$: spatial electron density distribution

So, we can deduce information about changes in the electron density distribution (e.g. a composition profile) by observing XRD data.



Multilayer structure and its XRD pattern

- Electron density distribution in the multilayer sample can be modeled as a square wave.
- The scattered amplitude is proportional to the Fourier series of the square wave given.
- The weighting of the $n=1$ (first order) harmonic wave reflects the degree of the interdiffusion.



$$\tilde{D} = \frac{-L^2}{8\pi^2} \frac{d}{dt} \ln \left[\frac{I(t)}{I(0)} \right]$$

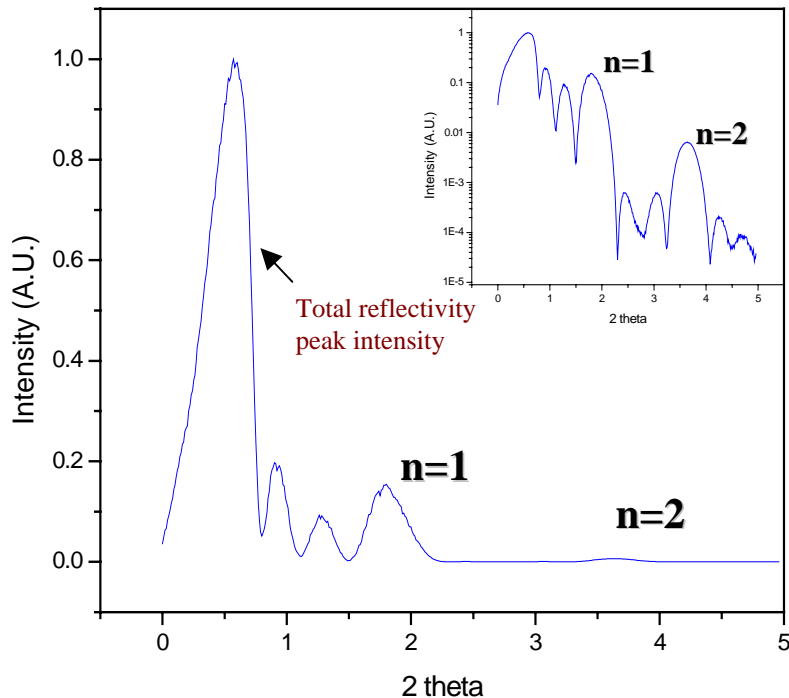
\tilde{D} : effective interdiffusivity

L : bilayer period

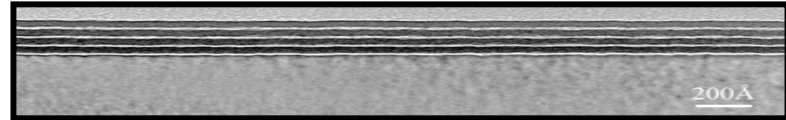
I : the first-order low-angle x-ray modulation peak



In-situ Low-angle XRD Studies



Low angle XRD data
for $(\text{SiO}_2/\text{HfO}_2)_4$ multilayer structure

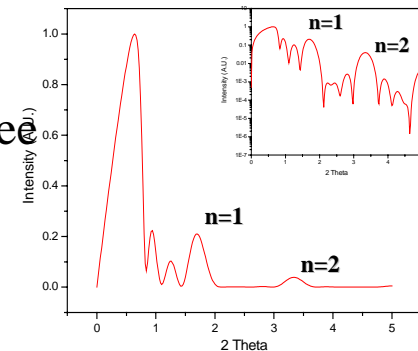


$\text{HfO}_2\text{-SiO}_2$ multilayer sample under study :
(by UV-Ozone Oxidation) *Courtesy of David Chi*

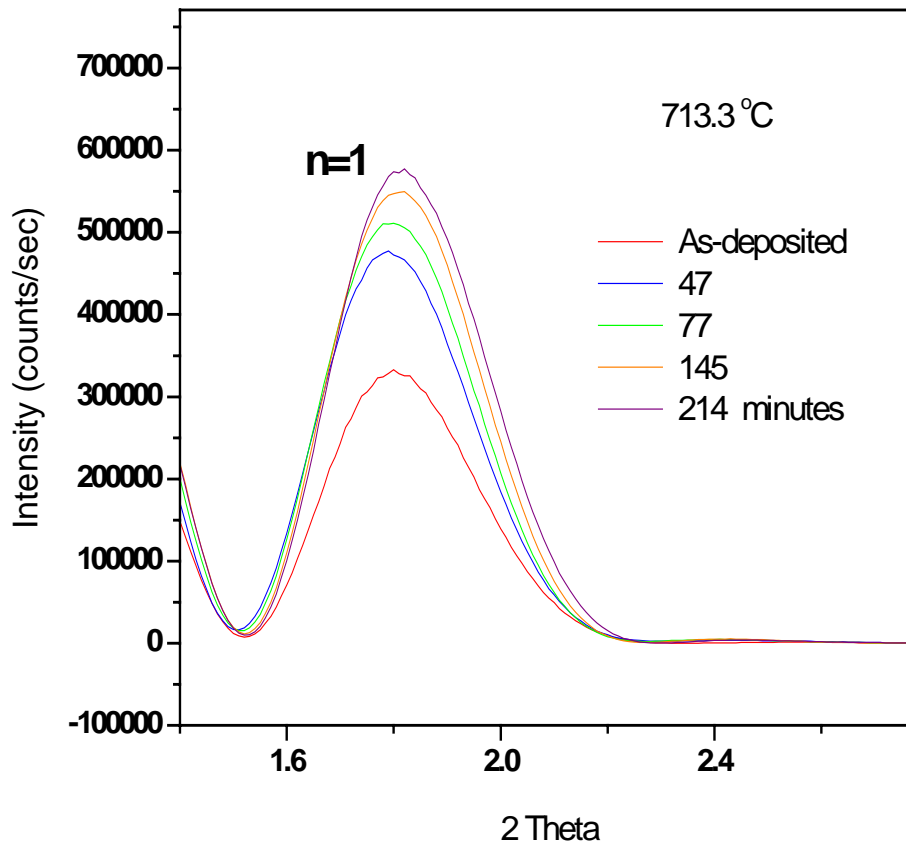
- The scattered intensity for N layers is given by:

$$I \propto \left(\sum_{n=0}^{N-1} f_n(q) e^{iq \cdot R_n} \right)^2 = f^2(q) \frac{\sin^2(Nq_z L / 2)}{\sin^2(q_z L / 2)}$$

Measured data agree well with the simulated result :



$(\text{HfO}_2/\text{SiO}_2)^*4$ structure, N_2 anneal



The intensity of $n = 1$ satellite peak *increases* as annealing proceeds

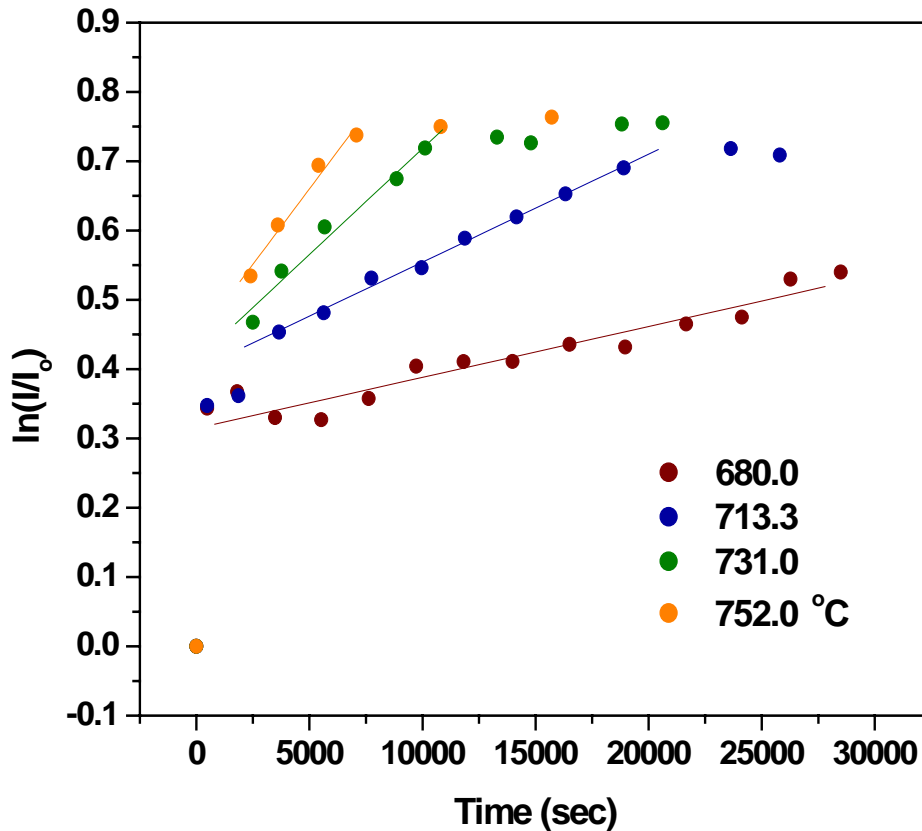


Evidence of phase separation at the initially-intermixed as-deposited $\text{HfO}_2/\text{SiO}_2$ interfaces



(HfO₂/SiO₂)*4 structure, N₂ anneal

(HfO₂/SiO₂)*4 structure, N₂ anneal

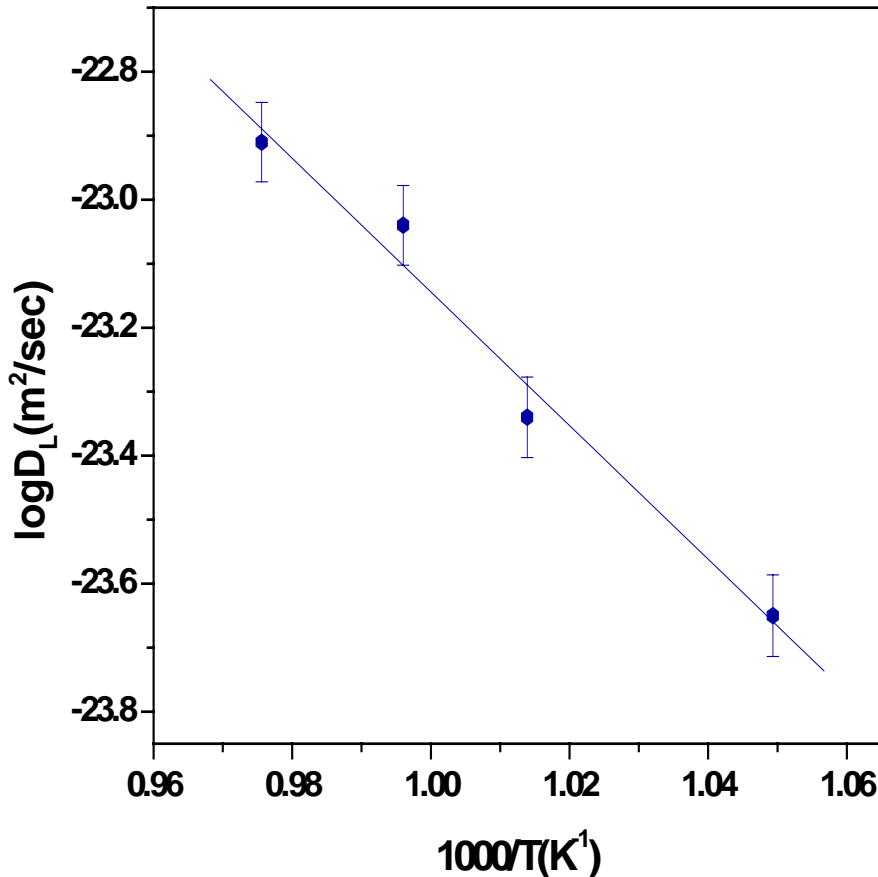


$$\tilde{D} = \frac{-L^2}{8\pi^2} \frac{d}{dt} \ln \left[\frac{I(t)}{I(0)} \right]$$

Temperature (°C)	Interdiffusivity(m ² /sec)
680.0	2.34*10 ⁻²⁴
713.3	5.65*10 ⁻²⁴
731.0	9.11*10 ⁻²⁴
752.0	25.18*10 ⁻²⁴



Activation energy for the phase separation



- The activation energy ΔH for phase separation can be obtained from the Arrhenius rate law :

$$D_e = D_o \exp\left(-\frac{\Delta H}{k_B T}\right)$$

- The obtained ΔH for the phase separation is $2.06 \pm 0.15 \text{ eV}$.



Summary

■ Accomplishments

- Used multilayer x-ray scattering to probe the kinetics of phase separation at as-deposited mixed HfO₂/SiO₂ interfaces
- Obtained the activation energy of 2.06 ± 0.15 eV for phase separation in HfO₂/SiO₂ interface system
- Determined temperature range for phase separation at initially-intermixed HfO₂/SiO₂ interface: $T > 650^\circ\text{C}$

